

Welcome Message

Welcome to SPLC 2017, the 21st International Systems and Software Product Line Conference. SPLC is the premier forum for practitioners, researchers and educators to present and discuss the most recent ideas, innovations, trends, experiences, and concerns in the area of systems and software product lines, software product family engineering and, more in general, systems family engineering. SPLC 2017 was held during September 25th to 29th, 2017, in Sevilla, Spain. This year the conference emphasis was on the future of the discipline.

SPLC 2017 included a highly selective program of research and industry papers, accompanied by workshops, demonstrations, tutorials, and keynote speeches. In total, the conference received 81 paper submissions: 49 research papers and 12 submissions between software and systems industry papers and future papers, as well as 16 data, demo and tool papers and 4 doctoral proposals. We also received 12 tutorials. We would like to thank all authors for their submissions.

Each submitted paper was reviewed by at least three Program Committee members. Based on the review reports and intensive discussions conducted electronically, the Program Committee selected 25 contributions for the research, industrial systems and software product lines and future of system and software product lines tracks, leaving us with an overall paper acceptance rate of 40%. The proceedings are presented in two volumes.

In addition, many recent excellent tools used in research and industry were shown in the tool demo track, and many new ideas were discussed during the doctoral symposium, workshops and tutorials tracks.

We would like to thank our keynote speakers, Jane Cleland-Huang and Marcello La Rosa for sharing their ideas and insights in their corresponding fields. A special mention goes to Don Batory and the Most Influential Paper (MIP) committee for the initiative that gave two awards for the first time. We would also like to thank the Program Committee members for their help with the selection of the papers, and the members of the Organizing and Local Committees whose efforts contributed to make the conference a success. Finally, we would like to thank our sponsors and institutional partners for their support and contributions. Special thanks go to Hitachi as our Platinum sponsor and to the University of Sevilla (Vicerrectorado de Relaciones Institucionales and Vicerrectorado de Investigación) for their financial and logistic support.

Sincerely,

Myra Cohen, Mathieu Acher, Lidia Fuentes, Daniel Schall, Jan Bosch, Rafael Capilla, Ebrahim Bagheri, Yingfei Xiong, Maurice ter Beek, Walter Cazzola, Oscar Díaz, Marcello La Rosa, Roberto E. López-Herrejón, Thomas Thüm, Javier Troya, Antonio Ruiz-Cortés and David Benavides